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## PRODUCT CHANGE NOTIFICATION

**PCN:** PCN182401

**Date:** June 13, 2018

**Subject:** Qualification of OSE-T as an Additional Assembly Site for Select Automotive Products

**To:** GENERAL INBOX  
 ELEMENT14  
 ProductChangeNotices@element14.com

**Change Type:** Major

### Description of Change:

Cypress announces the qualification of Orient Semiconductor Electronics, Taiwan (OSE-T) as an additional assembly site for select automotive products. These products are RoHS and REACH compliant. These products are assembled in the following package configurations.

The 28-Lead TSOP I (8x13.4x1.2mm) Pb-Free packages are assembled at OSE-T using the following Bill of Materials:

Material	OSE-T Bill of Materials	JCET Bill of Materials
Mold Compound	Sumitomo EMEG631SH	Kyocera G6000DA
Leadfinish	Pure Sn	NiPdAu
Die Attach Material	Sumitomo CRM-1076WA	Henkel QMI-509
Bond Wire	0.8 mil Au	1.0 mil Au

The 32-Lead TSOP I (8x13.4x1.2mm) Pb-Free packages are assembled at OSE-T using the following Bill of Materials:

Material	OSE-T Bill of Materials	JCET Bill of Materials
Mold Compound	Sumitomo EMEG631SH	Kyocera G6000DA
Leadfinish	Pure Sn	NiPdAu
Die Attach Epoxy	Sumitomo CRM-1076WA	Henkel QMI-509
Bond Wire	0.8 mil Au	1.0 mil Au

The 44-Lead TSOP II (11x18.5x1.2mm) Pb-Free packages are assembled at OSE-T using the following Bill of Materials:

Material	OSE-T Bill of Materials	JCET Bill of Materials
Mold Compound	Sumitomo EMEG631SH	Kyocera KEG6000DA
Leadfinish	Pure Sn	NiPdAu PPF
Die Attach Epoxy	Sumitomo CRM1076WA	Henkel QMI509
Bond Wire	0.8 mil Au	0.8 / 0.9 / 1.0 mil Au

The 48-Lead SSOP (7.50x15.87x2.60mm) Pb-Free packages are assembled at OSE-T using the following Bill of Materials:

Material	OSE-T Bill of Materials	JCET Bill of Materials
Mold Compound	Sumitomo EMEG700SLA	Kyocera KEG6000DA
Leadfinish	Pure Sn	NiPdAu
Die Attach Epoxy	Sumitomo CRM1076WA	Henkel QMI509
Bond Wire	0.8 mil Au	1.0 mil Au

The 32-Lead SOIC (11.30x20.45x3.00mm) Pb-Free packages are assembled at OSE-T using the following Bill of Materials:

Material	OSE-T Bill of Materials	JCET Bill of Materials
Mold Compound	Sumitomo EMEG631SH	Kyocera KEG6000DA
Leadfinish	Pure Sn	NiPdAu
Die Attach Epoxy	Sumitomo CRM1076WA	Henkel QMI509
Bond Wire	0.8 mil Au	1.0 mil Au

**Benefit of Change:**

Qualification of alternate manufacturing sites is part of the ongoing flexible manufacturing initiative announced by Cypress. The goal of the flexible manufacturing initiative is to provide the means for Cypress to continue to meet delivery commitments through dynamic, changing market conditions.

**Part Numbers Affected: 118**

See the attached 'Affected Parts List' file for a list of all part numbers affected by this change. Note that any new parts that are introduced after the publication of this PCN will include all changes outlined in this PCN.

**Qualification Status:**

These assembly sites have been qualified through a series of tests documented in the Qualification Test Plans summarized in the table below. These qualification reports can be found as attachments to this PCN or by visiting [www.cypress.com](http://www.cypress.com) and typing the QTP number in the keyword search window.

QTP Number	Qualification Reports
180411	OSE Taiwan as Additional Assembly Site 28-Lead TSOP
180418	OSE Taiwan as Additional Assembly Site 32-Lead TSOP
175106	OSE Taiwan as Additional Assembly Site 44-Lead TSOP
175107	OSE Taiwan as Additional Assembly Site 44-Lead TSOP
180301	OSE Taiwan as Additional Assembly Site 48-Lead SSOP
180705	OSE Taiwan as Additional Assembly Site 32-Lead SOIC

**Sample Status:**

Qualification samples may not be built ahead of time for all part numbers affected by this change. Please review the attached 'Affected Parts List' file for a list of affected part numbers with their associated OSE sample ordering part numbers. Samples are available now unless there is an indication that the sample ordering part numbers are subject to lead times. If you require qualification samples, please contact your local Cypress sales representative as soon as possible, preferably within 30 days of the date of this PCN, to place any sample orders.

**Approximate Implementation Date:**

Effective 90 days from the date of this notification or upon customer approval, whichever comes first, all shipments of Automotive non-PPAP part numbers in the attached file will be assembled at OSE-T or other approved assembly sites.

For Automotive PPAP part numbers this change will be effective upon customer approval.

**Anticipated Impact:**

Products assembled at the new site are completely compatible with existing products from form, fit, functional, parametric and quality performance perspectives.

Cypress also recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

**Method of Identification:**

Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

**Response Required:**

No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at [pcn\\_adm@cypress.com](mailto:pcn_adm@cypress.com).

Sincerely,

Cypress PCN Administration